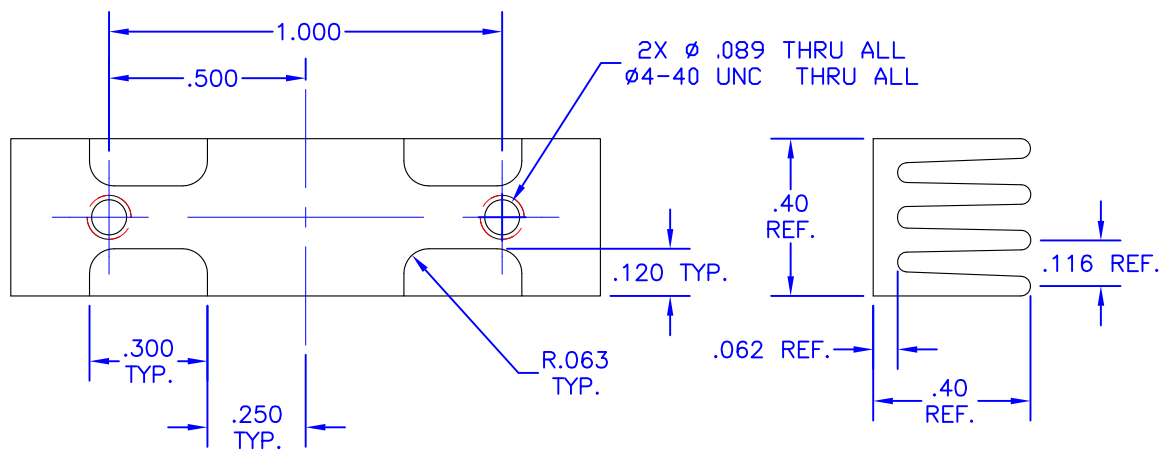
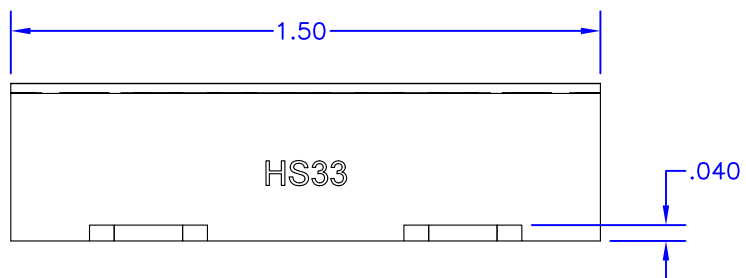
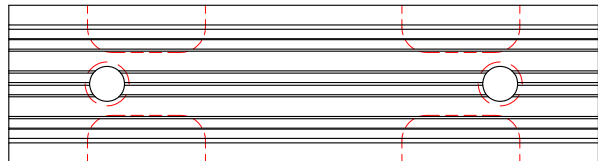


4

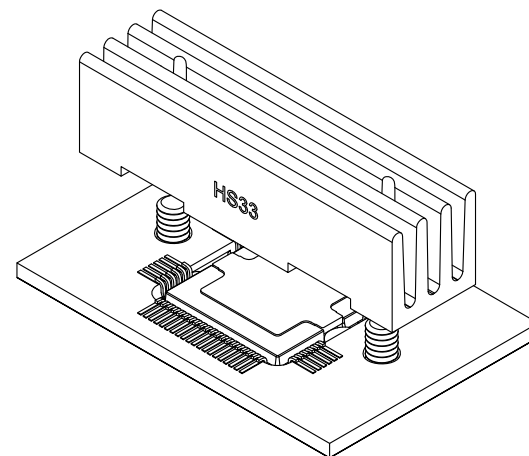
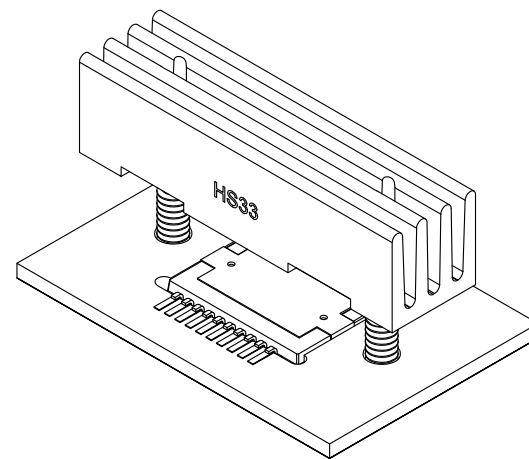
3

2

1



INVERTED THROUGH CIRCUIT BOARD
 MOUNTING WITH HEAT SINK
 (Patent Pending)



NOTES:

1. Unless otherwise noted, all dimensions are in inches.
2. Break all sharp edges, de-burr & remove loose chips.
3. Material: 6063-T5 aluminum alloy. Make from Aavid extrusion 70920
4. Mark with contrasting ink as shown, if specified by P.O.
5. Approximate Weight: 0.22 oz [6.3g]

TOLERANCES - UNLESS
 OTHERWISE SPECIFIED

.XX = $\pm$.05 [.002]

.XXX = $\pm$.005 [.0002]

ANG. = $\pm$ 2°



TITLE: **DK & HQ PACKAGE HEATSINK**

SUBJECT: **MECHANICAL DRAWING**

ENGINEERS: **D-M**

DRAWN BY: **P.ECK**

DCA: **12436**

SCL: **1**

OF: **1**

MODEL: **HS33**

FILENAME: **HS33**

REV: **B**

DATE: **14NOV12**

4

3

2

1